

# NAND Flash Code Information(1/3)

民间整理版 2016

**K** 9 X X X X X X X X - X X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory (K)

2. NAND Flash : 9

## 3. Small Classification

(SLC : Single Level Cell, MLC : Multi Level Cell,

SM : SmartMedia, S/B : Small Block)

1 : SLC 1 Chip XD Card

2 : SLC 2 Chip XD Card

3 : 4bit MLC Mono

4 : SLC 4 Chip XD Card

5 : MLC 1 Chip XD Card

6 : MLC 2 Chip XD Card

7 : SLC moviNAND

8 : MLC moviNAND

9 : 4bit MLC ODP

A : 3bit MLC MONO

B : 3bit MLC DDP

C : 3bit MLC QDP

D : TLC 16Die

F : SLC Normal

G : MLC Normal

H : MLC QDP

K : SLC Die Stack

L : MLC DDP

M : MLC DSP

N : SLC DSP

O : 3bit MLC ODP

P : MLC ODP

Q : SLC ODP

R : MLC 12-die stack

S : MLC 6 Die Stack

T : SLC SINGLE (S/B)

U : MLC 16 Die Stack

W : SLC 4 Die Stack

## 4~5. Density (Bit)

12 : 512M 16 : 16M 28 : 128M PG : 171G

32 : 32M 40 : 4M 56 : 256M QG : 341G

64 : 64M 80 : 8M 1G : 1G RG : 683G

2G : 2G 4G : 4G 8G : 8G SG : 1365G

AG : 16G BG : 32G CG : 64G KG : 1T

DG : 128G EG : 256G FG : 256G MG : 2T

GG : 384G HG : 512G LG : 24G

NG : 96G ZG : 48G 00 : NONE

## 6. Technology

0 : Normal (x8)

C : Catridge SIP

M : moviNAND

P : moviMCP

Z : SSD

1 : Normal (x16)

D : DDR Toggle 1.0

N : moviNAND FAB

T : Premium eSSD

Y : Toggle 2.0

B : Toggle 3.0

## 7. Organization

0 : NONE

8 : x8

6 : x16

## 8. Vcc

A : 1.65V~3.6V

B : 2.7V (2.5V~2.9V)

C : 5.0V (4.5V~5.5V)

D : 2.65V (2.4V ~ 2.9V)

E : 2.3V~3.6V

R : 1.8V (1.65V~1.95V)

Q : 1.8V (1.7V ~ 1.95V)

T : 2.4V~3.0V

S : 3.3V (3V~3.6V/ VccQ1.8V (1.65V~1.95V)

U : 2.7V~3.6V

V : 3.3V (3.0V~3.6V)

W : 2.7V~5.5V, 3.0V~5.5V 0 : NONE

## 9. Mode

0 : Normal

1 : Dual nCE & Dual R/nB

3 : Tri /CE & Tri R/B

4 : Quad nCE & Single R/nB

5 : Quad nCE & Quad R/nB

6 : 6 nCE & 2 RnB

7 : 8 nCE & 4 RnB

8 : 8 nCE & 2 RnB C : 16 CE

9 : 1st block OTP

A : Mask Option 1

L : Low grade

## 10. Generation

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

C : 4th Generation

D : 5th Generation

E : 6th Generation

Y : 25th Generation

Z : 26th Generation

# NAND Flash Code Information(2/3)

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## 11. "—"

### 12. Package

8 : TSOP1 (Lead-Free, Halogen-Free, CU)  
9 : 56TSOP1 (Lead-Free, Halogen-Free, CU)  
A : COB  
B : FBGA (Halogen-Free, Lead-Free)  
C : BGA 316  
D : 63-TBGA or BGA 316(new)  
E : ISM (Lead-Free, Halogen-Free)  
F : WSOP (Lead-Free)      G : FBGA  
H : BGA 132 or 136  
I : ULGA (Lead-Free) (12\*17)  
J : FBGA (Lead-Free)  
K : ULGA (Lead-Free, Halogen-Free) (12\*17)  
L : ULGA (Lead-Free, Halogen-Free) (14\*18)  
M : 52-ULGA (Lead-Free, Halogen-Free) (13\*18)  
P : TSOP1 (Lead-Free)  
Q : TSOP2 (Lead-Free)  
R : 56-TSOP1 (Lead-Free, Halogen-Free)  
S : TSOP1 (Lead-Free, Halogen-Free)  
T : WSOP (Lead-Free, Halogen-Free)  
U : COB (MMC)  
V : WSOP      W : Wafer  
X : BGA 88 or 108  
Y : TSOP1      Z : WELP (Lead-Free)

### 13. Temp

C : Commercial      I : Industrial  
S : SmartMedia  
B : SmartMedia BLUE  
0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

### 14. Customer Bad Block

B : Include Bad Block      E: Enterprise ?  
D : Daisychain Sample  
K : Special Handling  
L : 1~5 Bad Block  
N : ini. 0 blk, add. 10 blk  
S : All Good Block  
0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

### 15. Pre-Program Version

0 : None  
Serial (1~9, A~Z)

# NAND Flash Code Information(3/3)

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## 16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

| Divide    | Packing Type              | New Marking |
|-----------|---------------------------|-------------|
| Component | TAPE & REEL               | T           |
|           | Other ( Tray, Tube, Jar ) | 0 ( Number) |
|           | Stack                     | S           |
| Module    | MODULE TAPE & REEL        | P           |
|           | MODULE Other Packing      | M           |

## 17~18. Customer "Customer List Reference"